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**A DESIGN PERSPECTIVE
SECOND EDITION**

**JAN M. RABAEY
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*To Kathelijn, Karthiyayani, Krithivasan,
and our Parents*

"Qu'est-ce que l'homme dans la nature?

Un néant a l'égard de l'infini,

un tout al l'égard du néant,

un milieu entre rien et tout."

"What is man in nature?

Nothing in relation to the infinite,

everything in relation to nothing,

a mean between nothing and everything."

Blaise Pascal, *Pensées*, n. 4, 1670.

Maintaining the Spirit of the First Edition

While maintaining the spirit of the original has been a primary goal, the design team has also had to balance the need to update the content and visual style to reflect the current state of the art. This has been a challenge, as the original design was created in a time when the technology and design standards were very different. The team has worked to preserve the original's spirit while making necessary updates to the content and visual style. This has involved a careful review of the original text and design, as well as a consultation with the original designers. The result is a design that is both faithful to the original and updated to reflect the current state of the art.

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